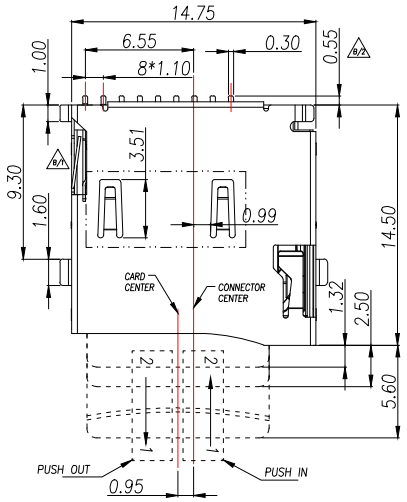
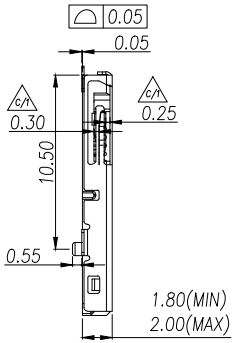
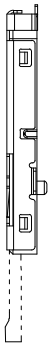
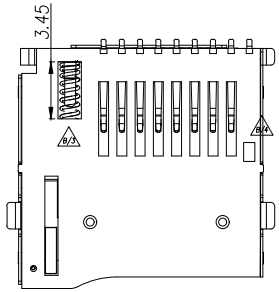
REV.	DESCRIPTION	ECN NO.	NAME	DATE









Specification:

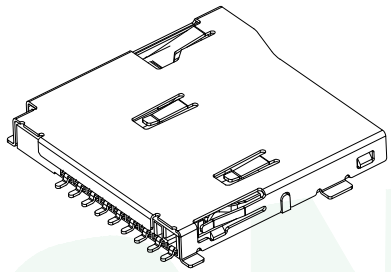
1.Electrical Characteristics:
- Contact Current Rating:0.5 Amperes.
- Dielectric Withstanding Voltage:AC500V r.m.s.
- Insulation Resistance:1000 MΩ Minimum.
- Contact Resistance:40 mΩ Maximum.

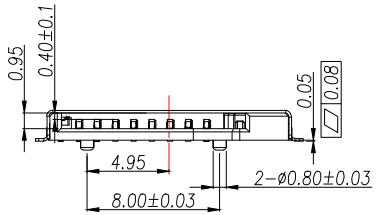
2.Environmental:
- Operating Temperature:-25°C~+90°C.

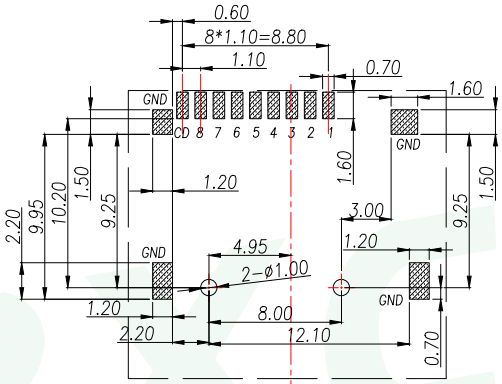
3.Environmental:
- Mating Cyeles:5,000 Insertions.

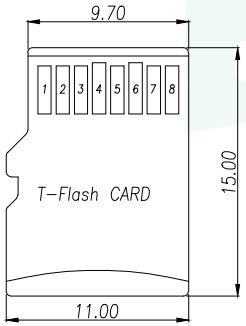
4.Mechanical Characteristics:
- Card Push Insertion/Out Force:0.2~1.40kgf.
- Contact Separation Force:0.20kgf Minimum.

5.Material:
- Insulator:HI-Temp Plastic UL 94V-0 Rated.
- Cantact:Copper Alloy(t=0.15mm).
- Shell:Stainless Steel(t=0.15mm).
- Spring:SWP.
- Salt spray time: 24H









PAD AREA

KEEP OUT AREA

RECOMMENDED PCB LAYOUT

GENERAL TOLERANCE ±0.05

Circuit Diagram for Detect Switch

WITHOUT CARD	OPEN	OPEN CD GND(SHELL)
INSERTING CARD	CLOSE	CLOSE CD GND(SHELL)

TF CARD PIN DEFINE

PIN NO.	NAME	YTPE	DESCRIPTION
1	DAT2	I/O/PP	DATE LINE(BIT2)
2	CD/DAT3	I/O/PP	CARD DETECT DATE LIN(BIT3)
3	CMD	PP	COMMAND RESPONSE
4	VDD	S	SUPPLY VOLTAGE
5	CLX	I	CLOCK
6	VSS	S	SUPPLY VOLTAGE GROUND
7	DATO	I/O/PP	DATE LINE(BITO)
8	DAT1	I/O/PP	DATE LINE(DIT1)

GENERAL TOLERANCE

DIM.	TOL.
X	
X.X	±0.30
X.XX	±0.25
X.XXX	±0.15
GENERAL ANGLE:	±3°

DONGGUAN BAOXUN PRECISION TECHNOLOGY CO., LTD

BXCONN®

TITLE: MICRO SD CARD PUSH PUSH SMT 镀金 双压片 外焊

DWG. NO.: TF02-TD9P

DRAWN: MAX

PART NO.: TF02-TD9P

CHECKED: ELLA

UNIT:	SCALE:	SHEET:	DWG. SIZE:	LAYER:
mm	none	1 of 1	A4	bxconn

APPROVED: WILL